

Trace impurity analysis

高純度石英玻璃之微量不純物分析

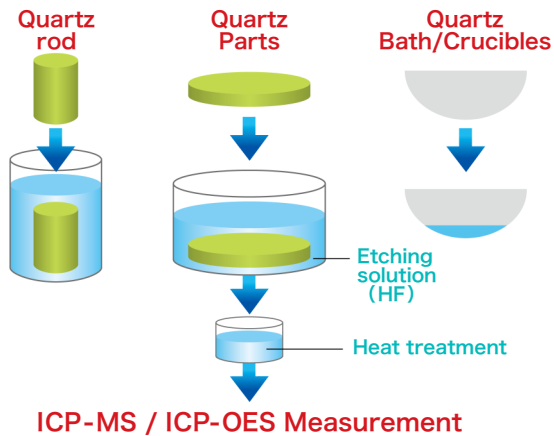
經由ICP-MS管理表面與表層金屬汙染

半導體製程裝置之治具、洗淨槽分析

半導體製程所指用石英玻璃治具，需為更高純度的石英製品。

ICP-MS 適用於分析高純度石英玻璃表面、表層與 Bulk 之金屬不純物分析。

< Flow of Quartz Analysis Method >



< Analytical Sample >

- 半導體製程裝置治具 (舟、爐芯管、環、加熱器)
- 洗淨槽
- 光罩材、晶圓
- 單晶拉坩堝

Quartz sample set up

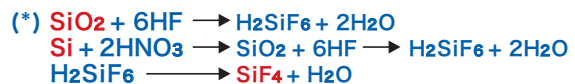
Sample preparation

- Metallic contamination on the outermost surface removal or no removal (as it is)
- ① Dissolution of surface contamination
② Decomposition of surface layer
ex.) 0-1um/1-2um/2-3um/.....
③ Total decomposition of sample
- Heat treatment (Si removal(*))

Measurement

- Determination of trace metal by ICP-MS
- Determination of Si by ICP-OES
- Calculation

Report



高純度石英玻璃治具之縱深分向金屬不純物分析

Depth (μm)	Bulk	0-1 (μm)	1-2 (μm)	2-3 (μm)	3-4 (μm)	Unit : ppb (ng/g)
Li	220	1500	1600	1300	1100	石英玻璃治具表層多層段分析結果與石英玻璃Bulk分析結果相比較，可以確定縱深分向的金屬不純物濃度。
Na	130	6500	920	560	500	
Mg	18	1100	300	130	60	
Al	15000	34000	35000	26000	19000	
K	240	5900	5200	4700	4200	
Ca	380	4100	2700	2000	1300	
Fe	56	710	260	180	140	
Cu	< 20	40	< 20	< 20	< 20	
ICP-OES SiO ₂ (g)		0.014	0.013	0.014	0.014	
Etching depth (μm)		1.00	0.94	0.99	1.03	